ABSTRACT

THICK FILM PLANARIZATION

Planarization of the top surfaces of layers that are more than about a micron thick is beset with problems not encountered in thinner layers. These problems have been overcome by means of a process that, initially allows the formation of 'horns' in the surface that is to be planarized. Said horns are then selectively etched away while other parts of the surface are protected, following which CMP is initiated and the surface gets planarized. A total of four embodiments are disclosed.

(Fig. 7)